



Material Content Data Sheet



Sales Product Name		BTT6030-1EKA		Issued		22. May 2015		
MA#		MA001369082						
Package		PG-DSO-14-47		Weight*		150.44 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	2.468	1.64	1.64	16402	16402
leadframe	inorganic material	phosphorus	7723-14-0	0.017	0.01		115	
	non noble metal	zinc	7440-66-6	0.069	0.05		460	
	non noble metal	iron	7439-89-6	1.383	0.92		9196	
wire	non noble metal	copper	7440-50-8	56.175	37.34	38.32	373411	383182
	non noble metal	copper	7440-50-8	0.624	0.41	0.41	4145	4145
	encapsulation	organic material	carbon black	1333-86-4	0.170	0.11		1129
plastics	plastics	epoxy resin	-	7.813	5.19		51934	
	inorganic material	silicondioxide	60676-86-0	76.939	51.16	56.46	511435	564498
leadfinish	non noble metal	tin	7440-31-5	2.503	1.66	1.66	16635	16635
plating	noble metal	silver	7440-22-4	1.470	0.98	0.98	9774	9774
glue	plastics	epoxy resin	-	0.141	0.09		939	
	noble metal	silver	7440-22-4	0.666	0.44	0.53	4425	5364
*deviation	< 10%				Sum in total:	100.00		1000000

Important Remarks:

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This product is in compliance with EU Directive 2011/65/EU (RoHS) and does not use any exemption.

Company	Infineon Technologies AG
Address	81726 München
Internet	www.infineon.com